



Notification of Product/Process Change

Doc. No.: 2224007

This letter intends as a formal notification of change to products which are currently supplied by ROHM Co., Ltd.

ROHM Co., Ltd. requires customers to provide acknowledgment of the receipt of this notification within 30 days from the date of this notice. Lack of acknowledgment of this notice within 30 days is considered as acceptance of the change.

After acknowledgement of the customer, lack of additional response within 90 day period constitutes acceptance of the change according to JEDEC Standard J-STD-046.

Your understanding and cooperation would be highly appreciated.

Issue Date: March 1, 2024

Title of change	SiC 3G Module change due to EOL of 4inch wafer	
Affected product(s)	Manufacturer part number	Customer part number
	BSM300D12P3E005,BSM400C12P3G002 BSM600D12P3G001	
Detailed description of change	Before	After
	SiC wafer diameter: 4inch Generation:3 Wafer FAB: ROHM APOLLO Co., Ltd. Chikugo plant	SiC wafer diameter: 6inch Generation: 3 or 4 Wafer FAB: LAPIS Semiconductor Co., Ltd. Miyazaki plant
Reason for change	-To increase production output by enhancing productivity and efficiency -End of production of 4-inch SiC wafers due to the transition to 6inch SiC wafers	
Anticipated impact on quality	There is no difference in reliability and electrical characteristics.	
Identification of change	Traceable by Lot code	
Planned first ship date	October 1, 2024	
Qualification plan schedule, results and samples	If required, please contact the local ROHM sales office or the authorized distributor.	
Comments	*Samples : Within 3 weeks from request	
Supplier contact	Please contact the local ROHM sales office or the authorized distributor.	
Notes		